

Recommended reflow soldering profile

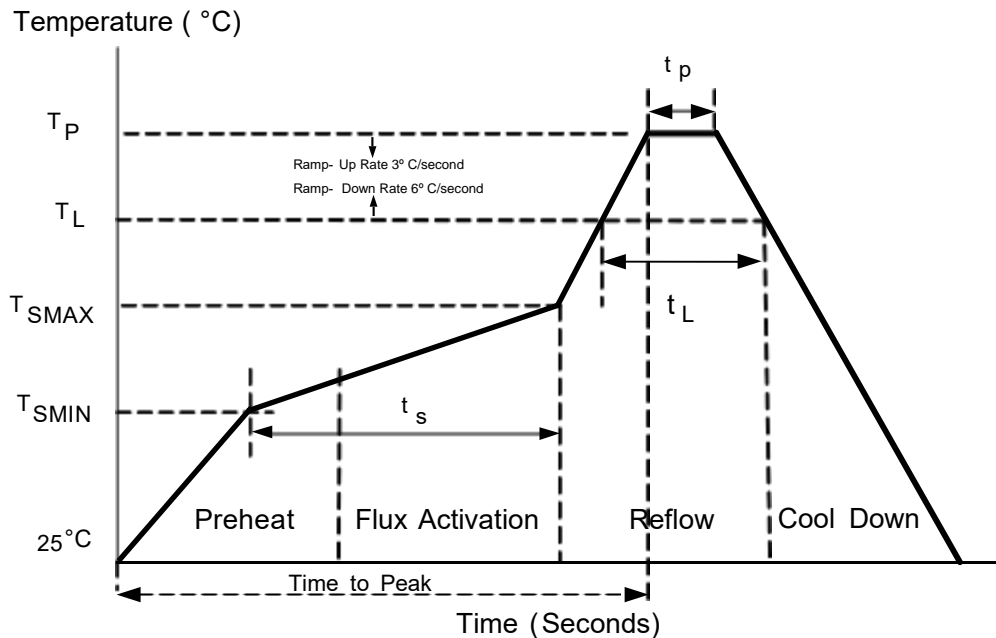


Figure 1. Temperature Profile for Infrared or Convection Reflow

Table 1. Reflow Profile

Parameter	Description	Pb-Free Package
Ramp- Up	Average Ramp- Up Rate (T_{SMAX} to T_P)	3 °C/second max.
T_{SMIN}	Preheat Peak Min. Temperature	150 °C
T_{SMAX}	Preheat Peak Max. Temperature	200 °C
T_P	Max. Reflow Temperature	260 (+0/-5) °C
T_s	Time between T_{SMIN} and T_{SMAX}	60- 180 seconds
T_L	Solder Melting Point	218 °C
t_L	Time Maintained above T_L	60- 150 seconds
t_p	Time within 5 °C of Peak Temperature	10 seconds
Ramp- Down	Ramp- down Rate	6 °C/second max.
Time to Peak	Time from 25 °C to Peak Temperature	8 minutes max.
Reflow Cycles	Number of Allowed Reflow Cycles	3

Recommended wave soldering profile

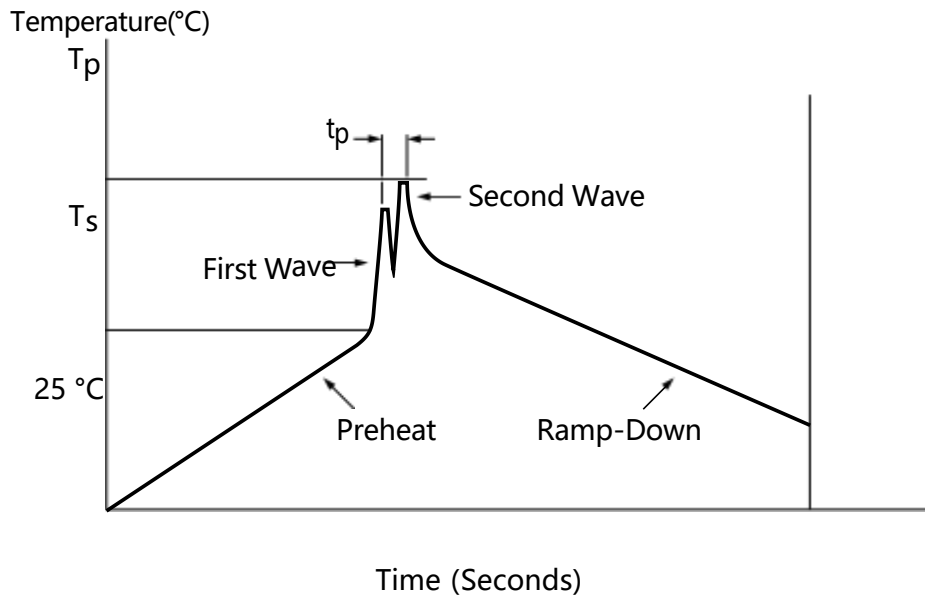


Figure 2. Temperature Profile for Wave Soldering

Table 2. Wave Soldering Profile

Parameter	Description	Pb-Free Package
Ramp-Up	Average Ramp-Up Rate	200°C/s
Heating	Heating Rate During Preheat	1 °C/s to 2 °C/s typical; 4 °C/S maximum
T_s	Final Preheat Temperature	130°C
T_p	Peak Temperature	260°C
t_p	Time Within Peak Temperature	10s
Ramp-Down	Ramp-Down Rate	5 °C/s maximum

Manual Soldering Specification

For manual soldering, GOFORD products can withstand 350 °C for 3 seconds, plsdo not exceed this limitation during soldering, otherwise the parts maybe damaged.